ABSTRACT

A semiconductor process chamber, semiconductor process equipment and a semiconductor process method are provided. The semiconductor process chamber includes: a reaction chamber; a transfer chamber below the reaction chamber, where the reaction chamber is connected to the transfer chamber through a bottom opening; a base with a lifting shaft connected to a bottom of the base, where the base is able to rise and descend between the reaction chamber and the transfer chamber through the bottom opening; and an elastic annular sealing structure. The annular sealing structure is below the base and surrounding the lifting shaft of the base. When the base descends into the transfer chamber, the base presses down and compress the annular sealing structure; and when the base rises into the reaction chamber and pressure on the annular sealing structure is released, the annular sealing structure stretches under its own elastic force until it abuts a bottom wall of the reaction chamber. to seal the bottom opening.

FIG. 4